

WEEK 4

BY: SAKSHAM RAO

1. Introduction / Background

This week's task explores transistor-level CMOS circuit behaviour via SPICE simulations using the SKY130 process models. The aim is to bridge device physics (MOSFET characteristics, sizing, variation) with digital timing fundamentals (delay, noise margin, slack) as used in static timing analysis (STA).

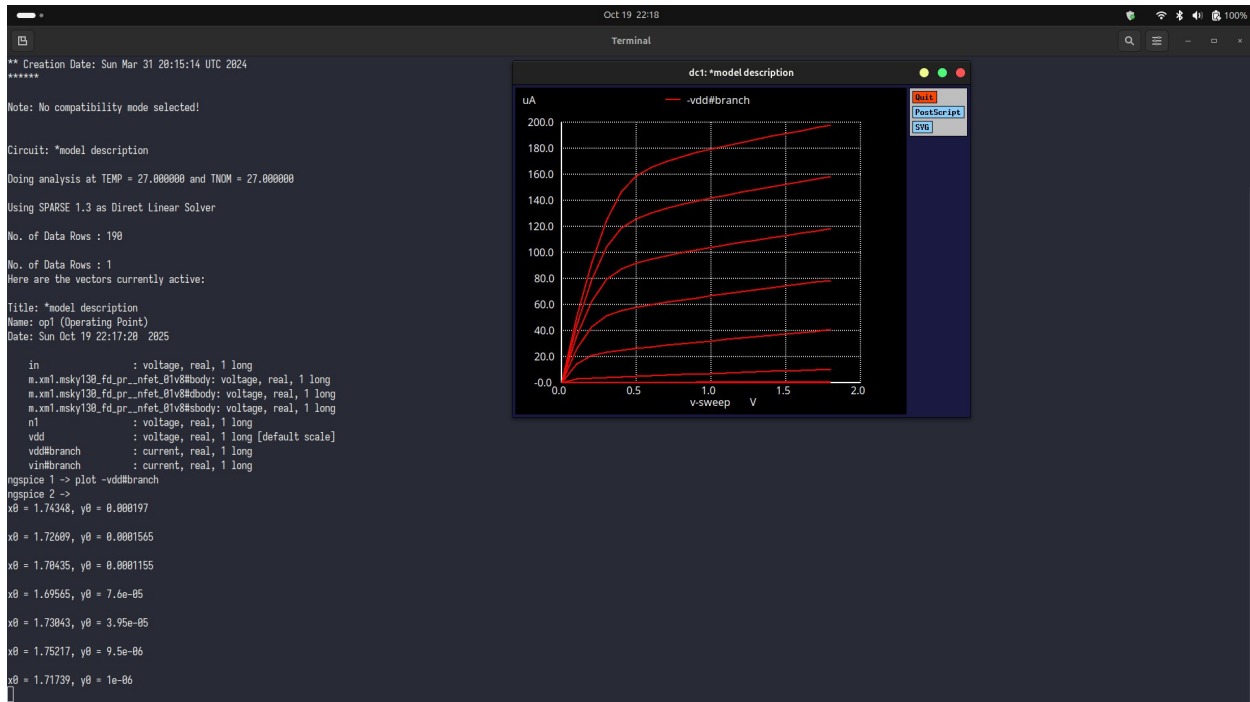
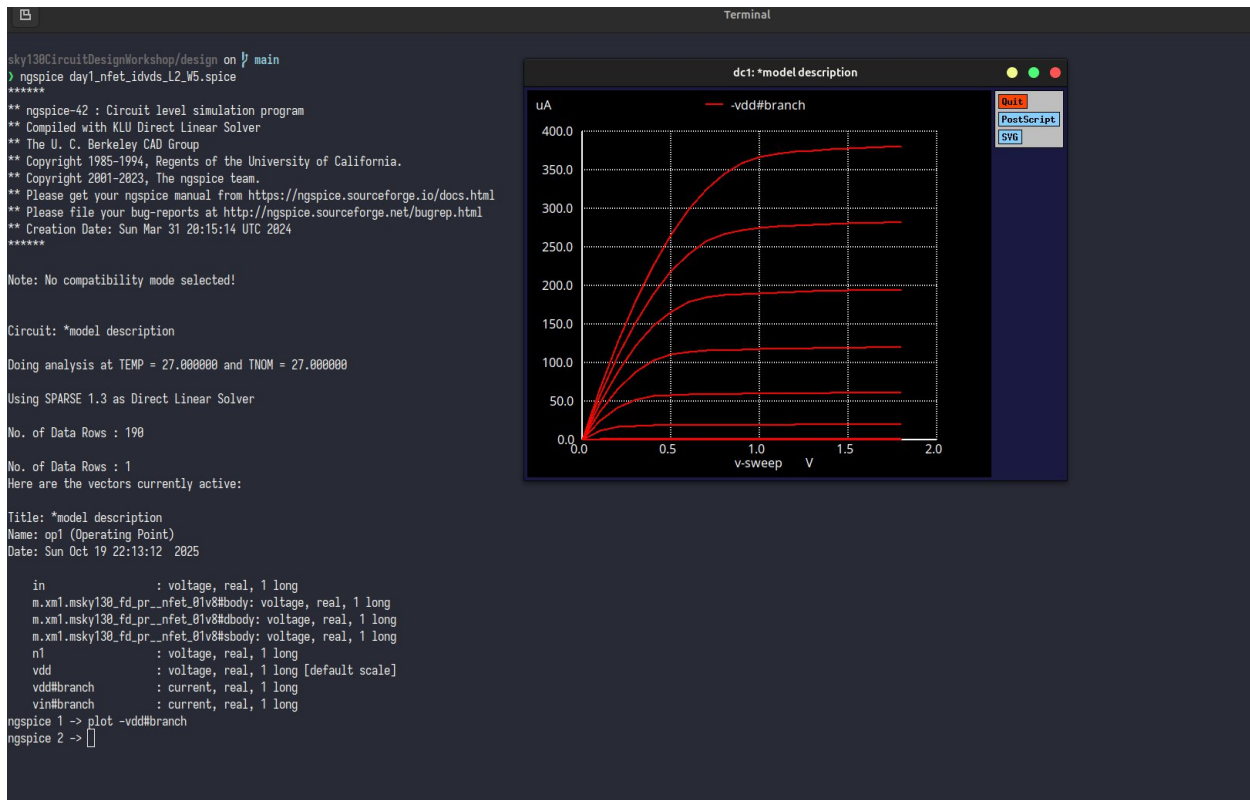
Specifically:

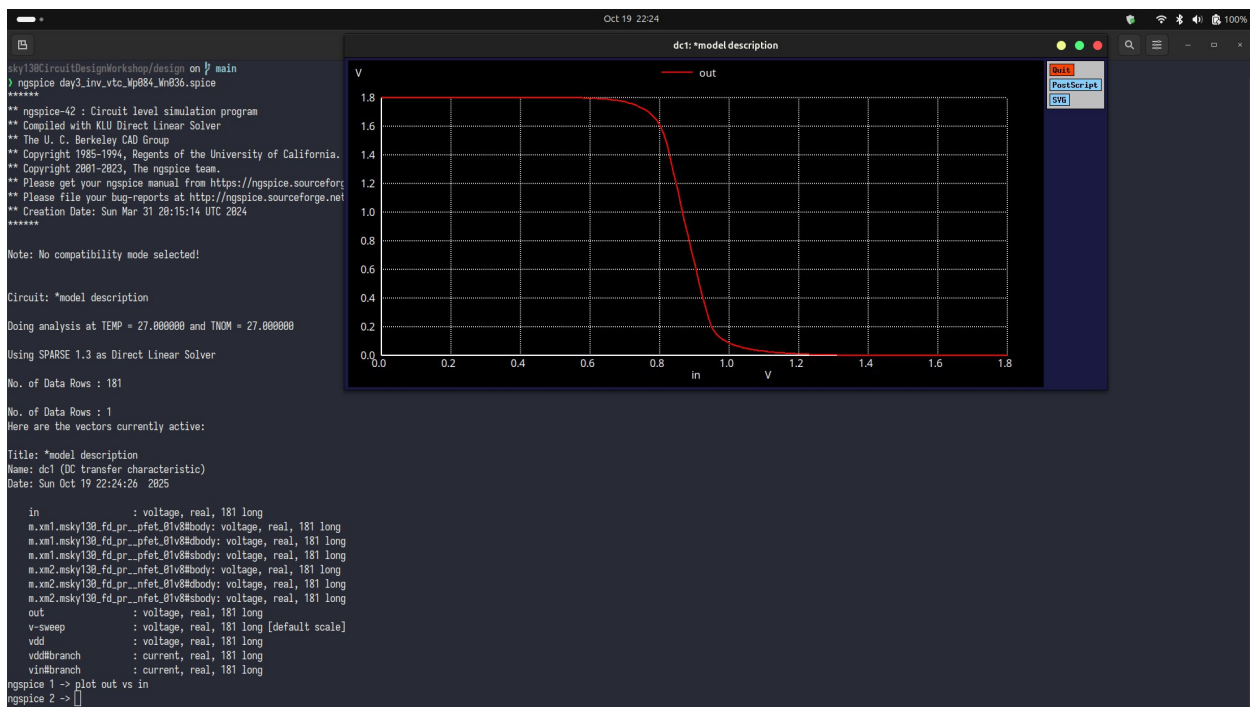
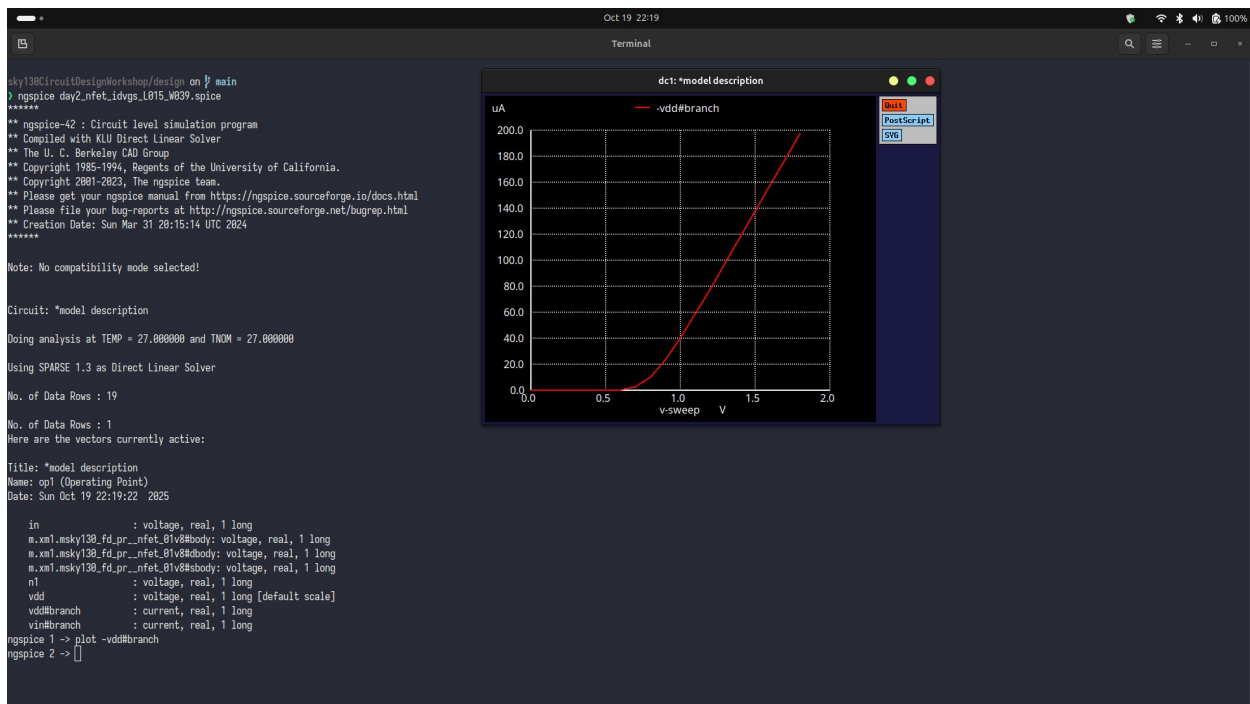
- We first examine how a MOSFET transitions between linear and saturation regions (I_d vs V_{ds}).
- We extract the threshold voltage (V_t) from I_d vs V_{gs} , and observe velocity-saturation effects in short-channel devices.
- We build a CMOS inverter and sweep its input to obtain the voltage transfer characteristic (VTC), identifying the switching threshold (V_m).
- We then perform transient simulation on the inverter to measure rise and fall propagation delays.
- Noise margins are determined from the VTC (V_{OL} , V_{OH} , V_{IL} , V_{IH} → NML, NMH).
- Finally we study variation: supply-voltage (V_{dd}) changes and transistor sizing changes (W/L) to see how inverter behaviour and timing margins shift.
By doing this, we gain intuition into how device-level variations propagate up into circuit timing and margin budgets used in STA.

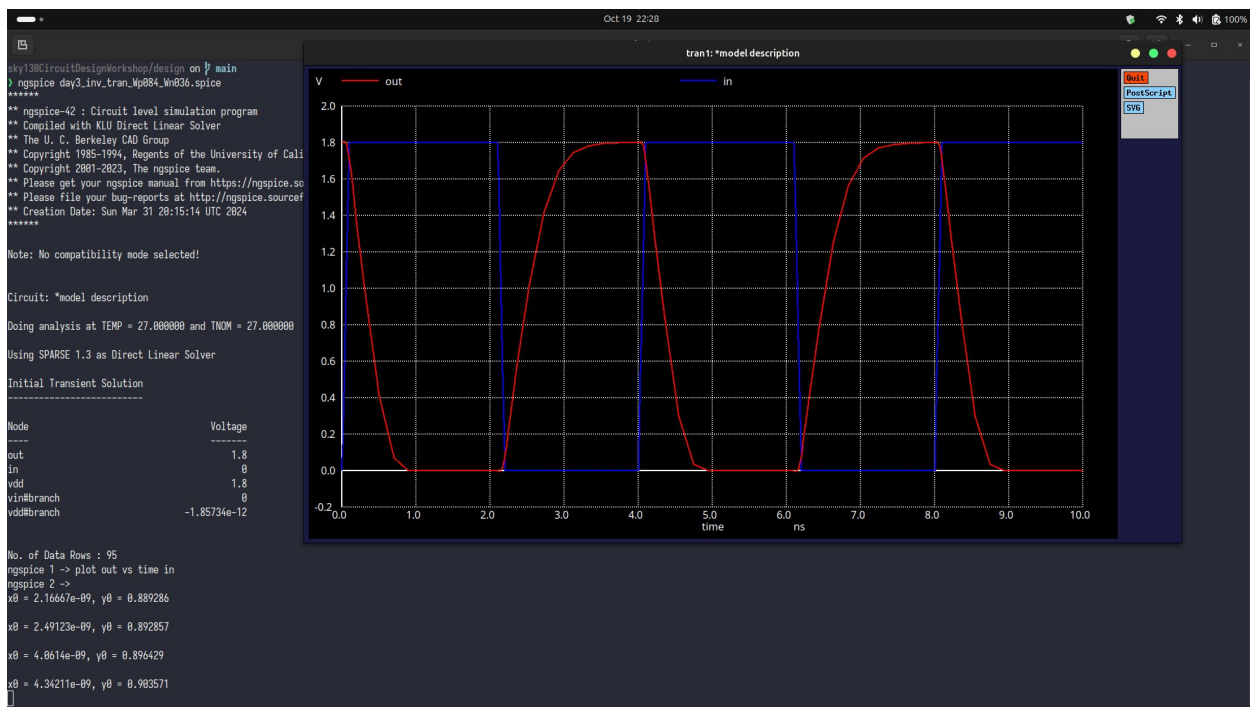
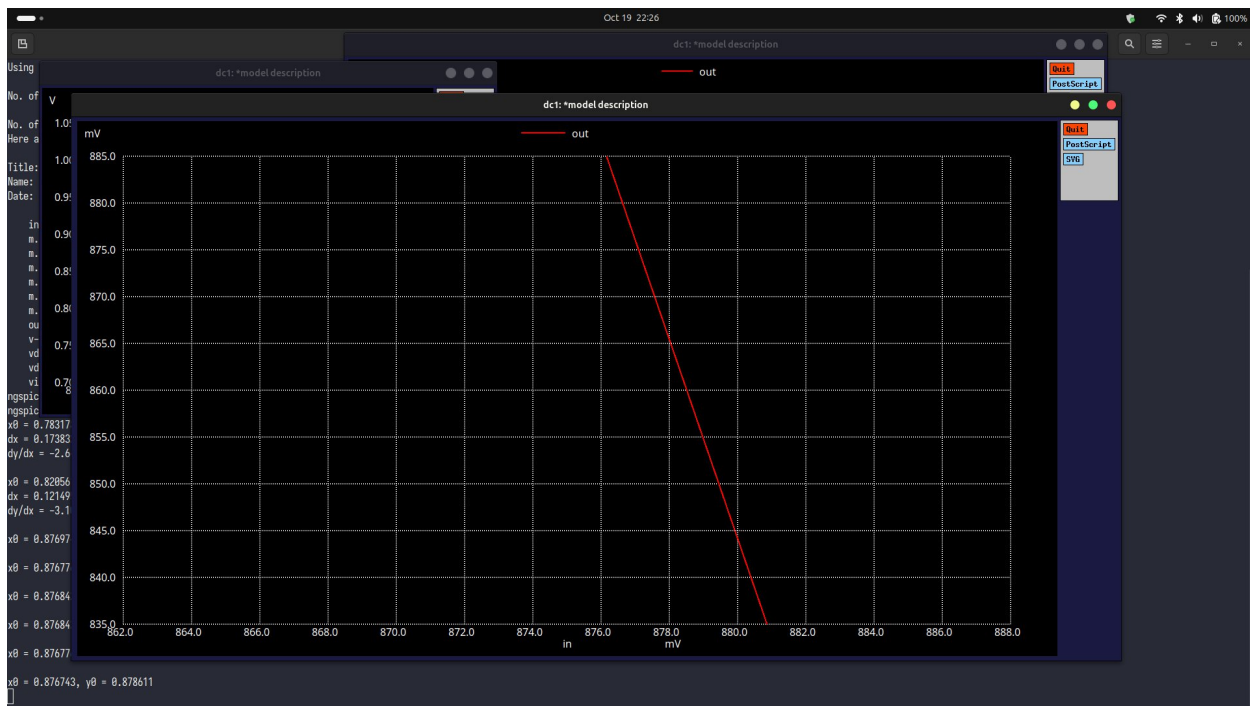
2. SPICE Netlist / Code References

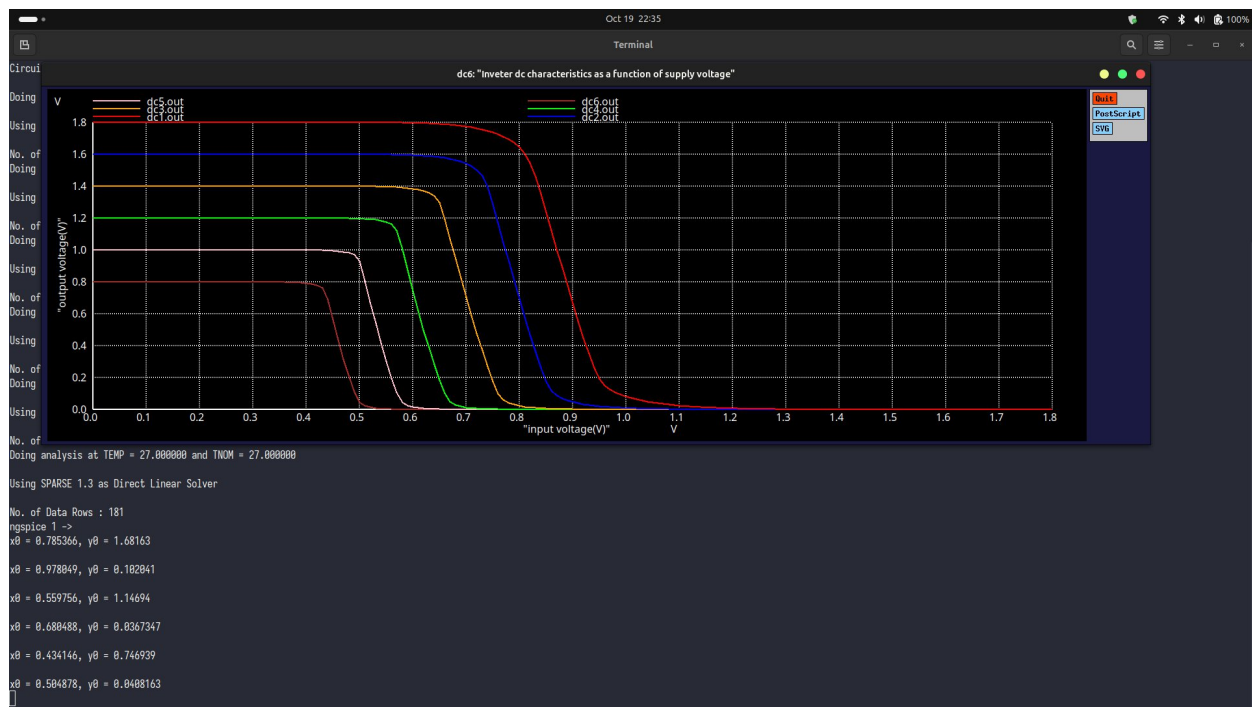
All nfet and pfet relevant to lab accessed directly from the github.

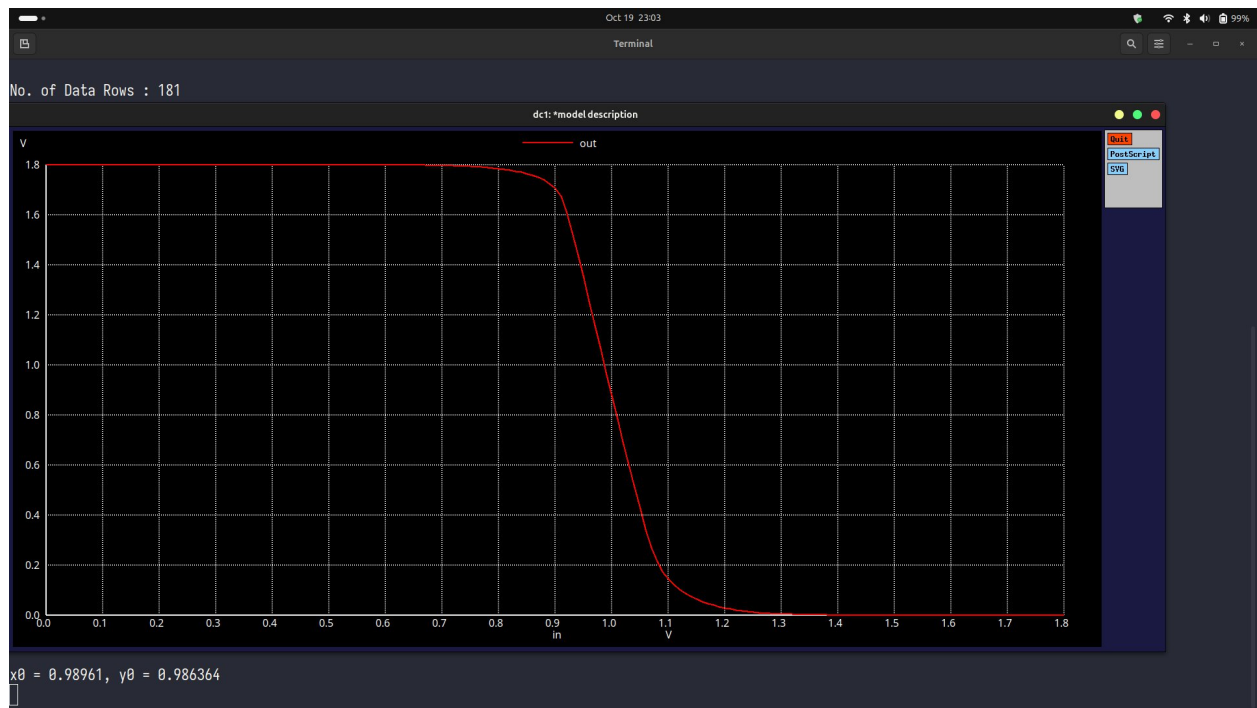
3. Plots & Figures











4. Tabulated Results

Below is a template table

Experiment	Condition	Extracted Parameter	Symbol	Value	Unit	Notes
NMOS Threshold Voltage	W=5 μm , L=2 μm , Vdd=1.8V	V _t	V _t	0.767	V	Method: $\sqrt{I_d}$ extrapolation / constant current
Inverter Switching Threshold	W _p =0.84 μm , W _n =0.39 μm , Vdd=1.8 V	V _m	V _m	0.876	V	V _{in} = V _{out} crossing
Inverter Rise Delay	W _p =0.84 μm , W _n =0.39 μm , Vdd=1.8 V	tp _{LH}	tp _{LH}	0.33	ns	50% input to 50% output
Inverter Fall Delay	same	tp _{HL}	tp _{HL}	0.28	ns	50% input to 50% output
Noise Margin Low	VTC at Vdd=1.8V	NML = V _{IL} – V _{OL}	NML	0.768	V	
Noise Margin High	same	NMH = V _{OH} – V _{IH}	NMH	0.621	V	
Device Variation: Switching Voltage	W _p =7 μm , W _n =0.42 μm , Vdd=1.8 V	V _m	V _m	0.989	V	V _{in} = V _{out} crossing

5. Observations / Analysis

A. MOSFET Id vs Vds

- At low V_{ds}, I_d increases approximately linearly with V_{ds}; beyond a certain V_{ds}, I_d saturates (becomes nearly flat) for each V_{gs}. For higher V_{gs} values, the saturation current is higher. There may be a slight slope in saturation region representing channel-length modulation.
- In the linear region the channel is fully formed and behaves like a resistor; once V_{ds} exceeds (V_{gs}–V_t), the channel pinches off at the drain end and further increase in V_{ds} gives only modest increase in current (saturation). In short-channel devices, velocity saturation and channel shortening reduce the slope, and the remaining slope is due to channel-length modulation (finite output resistance).

- The saturation region current sets the drive strength of the device. The finite output resistance (r_{out}) in saturation means that the device cannot be considered ideal switch — it will impact how fast a node can be driven (i.e., its delay) and how large the load it can drive. Variation in this behaviour translates into variation of propagation delay and slack margin in STA.

B. NMOS I_d vs V_{gs} (Threshold Extraction)

- : The I_d vs V_{gs} curve shows a threshold-like kink where current starts to rise sharply. On a $\sqrt{I_d}$ vs V_{gs} plot (for long-channel behaviour) you can extrapolate the linear portion back to zero to get V_t . In a short-channel device you may see a more gradual increase due to velocity saturation.
- : V_t is the gate-voltage at which a strong inversion channel forms and significant current begins to flow. In short-channel devices velocity saturation occurs when the carriers cannot gain further velocity despite higher lateral field; this flattens the I – V rise and complicates threshold definition.
- V_t variation (due to process, temperature, voltage) shifts the device's drive strength and switching point of gates. In timing paths, a higher V_t usually slows devices (lower current) and may increase slack negative margin, while a lower V_t increases leakage and may affect noise margins.

C. CMOS Inverter VTC

- The VTC (V_{out} vs V_{in}) shows a steep transition region where the inverter switches, typically around some V_m point (where $V_{in} = V_{out}$). The gain (dV_{out}/dV_{in}) is high around that region. On the left region (V_{in} low) V_{out} is near V_{dd} (PMOS on), on right region (V_{in} high) V_{out} is near 0 (NMOS on).
- As input increases, the NMOS begins to conduct and the PMOS begins to turn off; at the crossover point both devices conduct significantly so the output is dragged from high to low (or vice versa). The sizing ratio ($W_p:W_n$) and the device characteristics determine the exact switching point V_m .
- V_m effectively sets the logic threshold of the gate and influences when the next stage sees a valid “0” or “1” transition. The steepness of VTC (gain) affects noise margin and the robustness of logic levels; thus better understanding of VTC helps in margin budgeting in timing and noise analysis.

D. Transient Simulation – Rise/Fall Delays

- The output waveform follows the input pulse with some delay; the time between the input crossing 50% and output crossing 50% defines t_{pLH} for rising transition and t_{pHL} for falling transition. Often one of t_{pLH}/t_{pHL} is longer, e.g., rise may be slower.
- The delay arises due to the RC charging/discharging of the load through the MOSFETs; PMOS and NMOS have different mobilities (holes slower), meaning the rise (through PMOS) often is slower than the fall (through NMOS) unless sizing compensates. Capacitances (load, parasitic) and drive current define the delay.

- Propagation delay is key for STA: launch-to-capture timing, clock period budgeting, and slack calculation. Understanding factors affecting delay (loading, sizing, supply) gives better insight on how to optimise critical paths.

E. Noise Margin / Robustness Analysis

- From the VTC you can extract VOL (output low), VOH (output high), VIL and VIH (input threshold points where gain = -1 or some defined point). Then noise margins NML and NMH quantify how much noise the gate can tolerate.
- The logic levels and transition region define how resilient the logic gate is to input noise or variation. A larger noise margin means more robust logic. Sizing, threshold voltages, and supply affect these margins.
- In timing and sign-off, noise margins are akin to margin budgets — if noise or variation consumes margin, then slack is reduced. Robust logic design means you must allow margin not only for timing but also for noise/variations.

F. Power-Supply and Device Variation Studies

- Varying Vdd shifts the VTC (V_m moves, gain may reduce), and increases delay (at lower Vdd the current is less). Changing transistor sizes (e.g., W/L ratio) shifts V_m and affects drive strength and hence delay. Noise margins similarly change.
- Supply voltage affects overdrive ($V_{gs} - V_t$) and hence current; smaller supply \Rightarrow lower drive current \Rightarrow slower device. Sizing changes affect ratio of PMOS/NMOS strengths and thus switching threshold. Variations in process (device size, mobility, threshold) propagate to circuit behaviour.
- STA typically considers PVT corners (process, voltage, temperature) explicitly. These variation studies at the transistor/circuit level show why corners exist and how slack/critical path margin can degrade under worst-case conditions. Understanding this physically helps anticipate where timing margin may vanish or variation may dominate.

6. Conclusions

- This set of SPICE- based experiments show clearly how transistor-level phenomena (threshold voltage, velocity saturation, channel length modulation, sizing and supply variation) affect circuit-level timing and noise behaviour.
- The behaviour we measured (switching thresholds, delays, noise margins) are the building blocks of what STA approximates when analysing large digital designs. By seeing the physical device behaviour, we gain better intuition for timing budgets, margin setting, and variation impacts.
- Device sizing, supply voltage, and process variation all contribute to timing slack tightening – this underscores the importance of conservative margins in digital design.
- In real design flows (such as considered in the sky130 workshop), these principles underlie how standard-cells are characterised, how timing models are built, and how PVT corners are defined.

- Overall, bridging SPICE simulation and STA concepts strengthens your understanding of how “what happens in the transistor” affects “what happens in the digital circuit and timing path”.

7. References

- Repository: sky130CircuitDesignWorkshop (GitHub) —
<https://github.com/kunalg123/sky130CircuitDesignWorkshop> (GitHub)